

N-Ch 100V Fast Switching MOSFETs

Features:

- ★ Super Low Gate Charge
- ★ Excellent Cdv/dt effect decline
- ★ Green Device Available
- ★ Advanced high cell density Trench technology

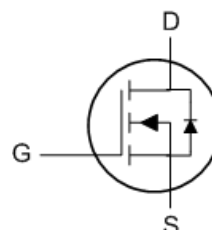


Description:

The KEP0016 is the high cell density trenched N-ch MOSFETs, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The KEP0016 meet the RoHS and Green Product requirement, 100% EAS guaranteed with full function reliability approved.

TO220 Pin Configuration



Product Summary

BVDSS	RDSON	ID
100V	47mΩ	27A

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	100	V
V_{GS}	Gate-Source Voltage	± 20	V
$I_D@T_C=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^1$	27	A
$I_D@T_C=100^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^1$	17	A
$I_D@T_A=25^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^1$	4.2	A
$I_D@T_A=70^{\circ}C$	Continuous Drain Current, $V_{GS} @ 10V^1$	3.3	A
I_{DM}	Pulsed Drain Current ²	54	A
EAS	Single Pulse Avalanche Energy ³	36.5	mJ
I_{AS}	Avalanche Current	27	A
$P_D@T_C=25^{\circ}C$	Total Power Dissipation ⁴	87	W
$P_D@T_A=25^{\circ}C$	Total Power Dissipation ⁴	2	W
T_{STG}	Storage Temperature Range	-55 to 150	$^{\circ}C$
T_J	Operating Junction Temperature Range	-55 to 150	$^{\circ}C$

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ¹	---	62	$^{\circ}C/W$
$R_{\theta JC}$	Thermal Resistance Junction-Case ¹	---	1.44	$^{\circ}C/W$

Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	100	---	---	V
ΔBV _{DSS} /ΔT _J	BVDSS Temperature Coefficient	Reference to 25 °C, I _D =1mA	---	0.098	---	V/°C
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =20A	---	---	47	mΩ
		V _{GS} =4.5V, I _D =15A	---	---	50	
V _{GS(th)}	Gate Threshold Voltage	V _{GS} =V _{DS} , I _D =250uA	1.0	---	2.5	V
ΔV _{GS(th)}	V _{GS(th)} Temperature Coefficient		---	-5.52	---	mV/°C
I _{DSS}	Drain-Source Leakage Current	V _{DS} =80V, V _{GS} =0V, T _J =25 °C	---	---	10	uA
		V _{DS} =80V, V _{GS} =0V, T _J =55 °C	---	---	100	
I _{GSS}	Gate-Source Leakage Current	V _{GS} =±20V, V _{DS} =0V	---	---	±100	nA
g _{fs}	Forward Transconductance	V _{DS} =5V, I _D =20A	---	28.7	---	S
R _g	Gate Resistance	V _{DS} =0V, V _{GS} =0V, f=1MHz	---	1.6	---	Ω
Q _g	Total Gate Charge (10V)	V _{DS} =80V, V _{GS} =10V, I _D =20A	---	60	---	nC
Q _{gs}	Gate-Source Charge		---	9.7	---	
Q _{gd}	Gate-Drain Charge		---	11.8	---	
T _{d(on)}	Turn-On Delay Time	V _{DD} =50V, V _{GS} =10V, R _G =3.3Ω I _D =20A	---	10.4	---	ns
T _r	Rise Time		---	46	---	
T _{d(off)}	Turn-Off Delay Time		---	54	---	
T _f	Fall Time		---	10	---	
C _{iss}	Input Capacitance	V _{DS} =15V, V _{GS} =0V, f=1MHz	---	3848	---	pF
C _{oss}	Output Capacitance		---	137	---	
C _{rss}	Reverse Transfer Capacitance		---	82	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I _S	Continuous Source Current ^{1,5}	V _G =V _D =0V, Force Current	---	---	27	A
I _{SM}	Pulsed Source Current ^{2,5}		---	---	54	A
V _{SD}	Diode Forward Voltage ²	V _{GS} =0V, I _S =1A, T _J =25 °C	---	---	1.2	V
t _{rr}	Reverse Recovery Time	I _F =20A, dI/dt=100A/μs, T _J =25 °C	---	30	---	nS
Q _{rr}	Reverse Recovery Charge		---	37	---	nC

Note :

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper.
- 2.The data tested by pulsed, pulse width ≤ 300us, duty cycle ≤ 2%
- 3.The EAS data shows Max. rating. The test condition is V_{DD}=25V, V_{GS}=10V, L=0.1mH, I_{AS}=27A
- 4.The power dissipation is limited by 150 °C junction temperature
- 5.The data is theoretically the same as I_D and I_{DM}, in real applications, should be limited by total power dissipation.

Typical Characteristics

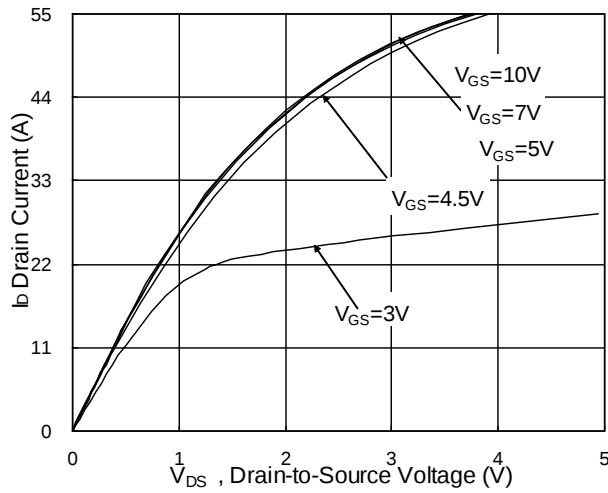


Fig.1 Typical Output Characteristics

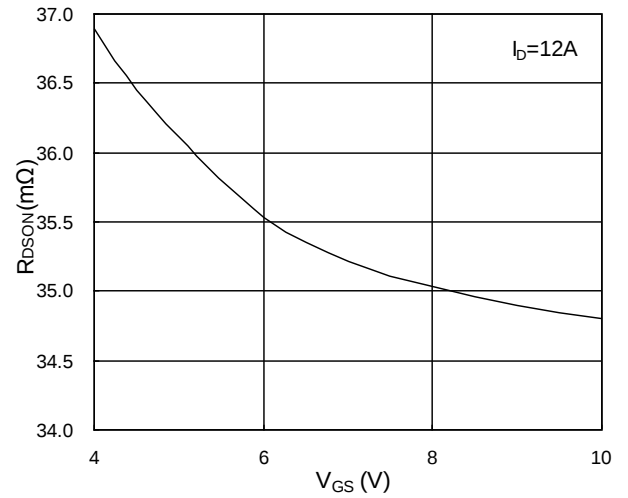


Fig.2 On-Resistance vs. Gate-Source

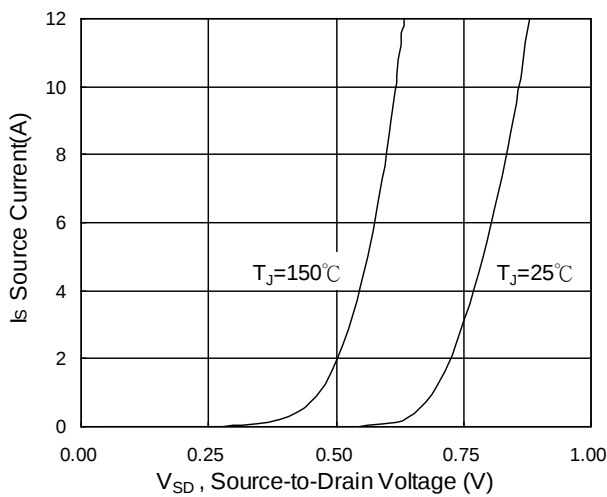


Fig.3 Forward Characteristics Of Reverse

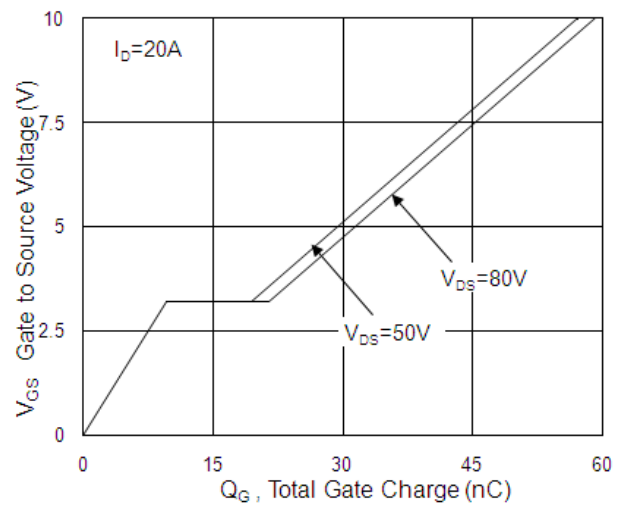


Fig.4 Gate-Charge Characteristics

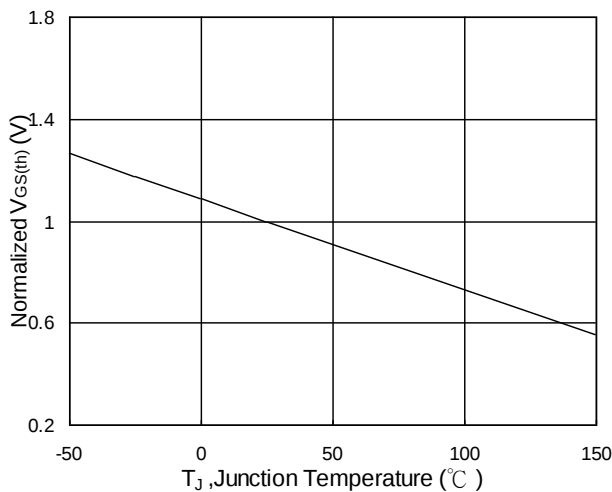


Fig.5 Normalized $V_{GS(th)}$ vs. T_J

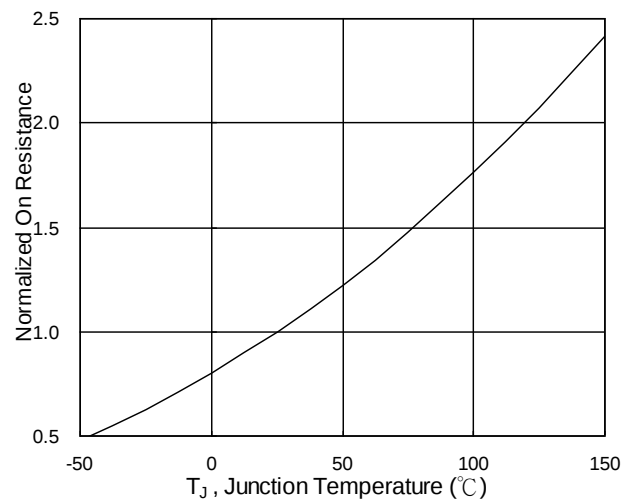
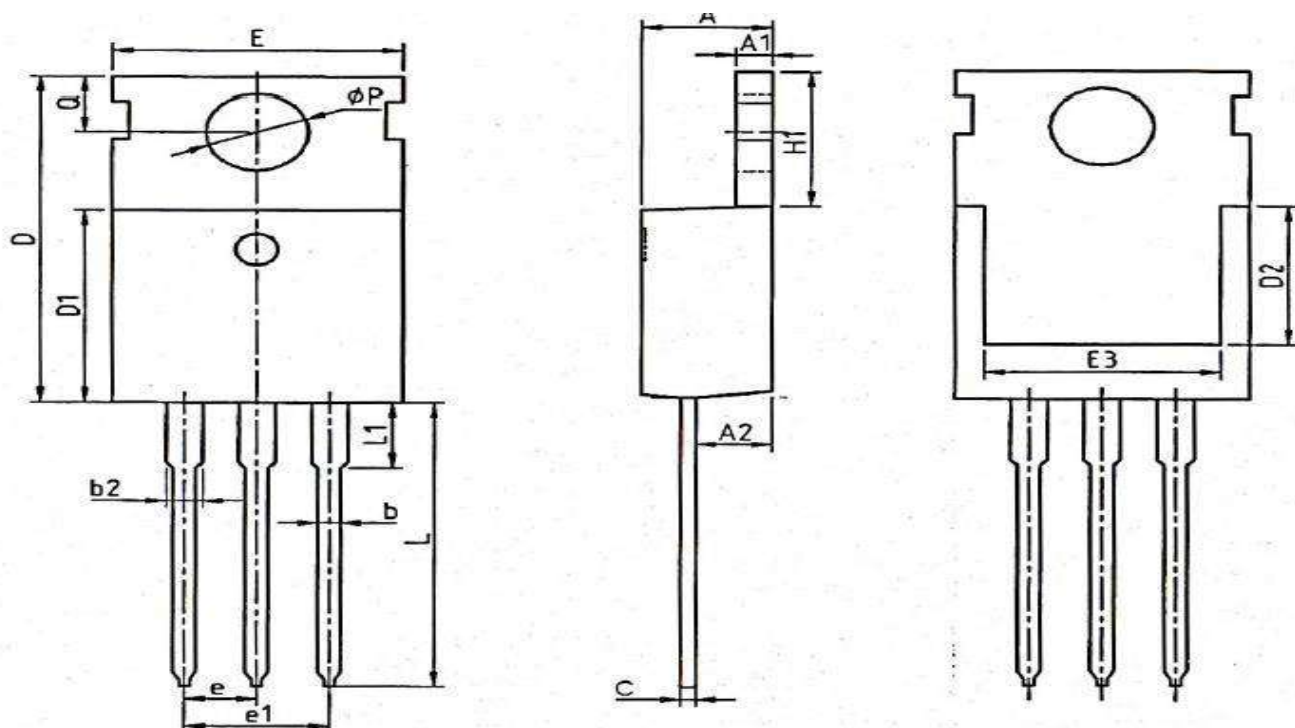


Fig.6 Normalized $R_{DS(on)}$ vs. T_J

TO-220_3L Package Outline



SYMBOLS	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	3.556	4.826	0.14	0.19
A1	0.508	1.4	0.02	0.055
A2	2.032	2.921	0.08	0.115
b	0.381	1.016	0.015	0.04
b2	1.143	1.778	0.045	0.07
c	0.356	0.61	0.014	0.024
D	14.224	16.51	0.56	0.65
D1	8.382	9.017	0.33	0.355
D2	5.5	-	0.216	-
E	9.652	10.668	0.38	0.42
E3	6.858	-	0.27	-
e	2.540 BSC		0.100 BSC	
e1	5.080 BSC		0.200 BSC	
H1	5.842	6.858	0.23	0.27
L	12.7	14.732	0.5	0.58
L1	-	4.06	-	0.16
Q	2.54	3.048	0.1	0.12